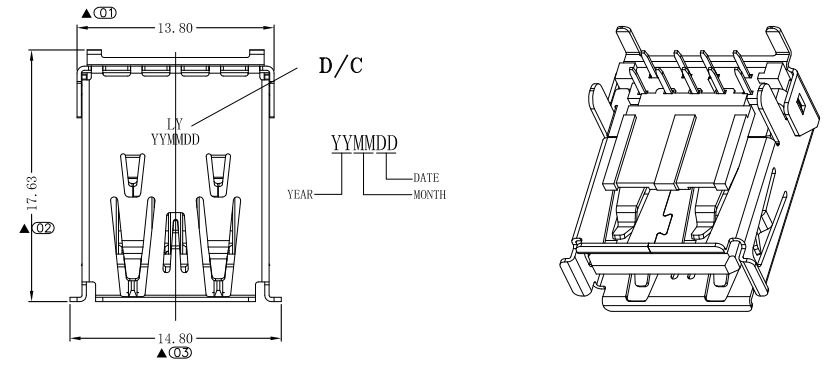


正式图 参考图

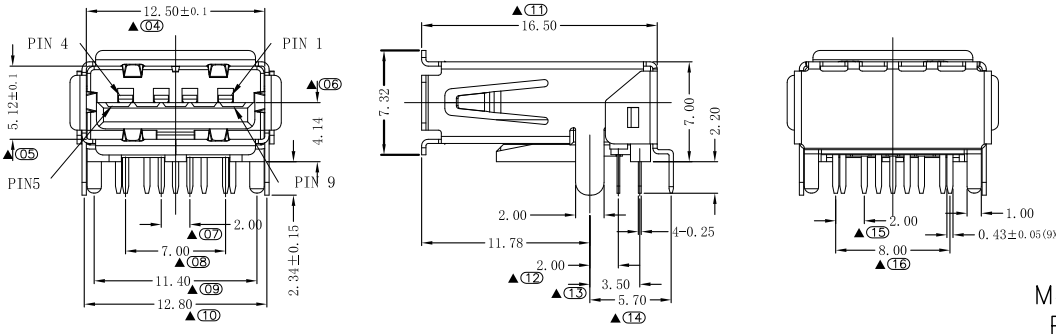
6	7	8		
Mark	ECN NO.	DESCRIPTION	DESIGN	Date:
---	---	NEW VERSION	Peter Wang	2018.08.31



- NOTES:
- 1.Rating: DC30V 1.8A;
 - 2.Contact Resistance:≤30Milliohm;
 - 3.Insulation Resistance:≥100Megohm;
 - 4.Withstand Voltage:AC500V for one minute;
 - 5.MATING FORCE:35 N Max
UNMATED FORCE:10 N Min INITIAL; 8 N Min AFTER TEST
 - 6.Life test:5000Cycles.
 - 7.Operating Temperature:−25°C~+70°C 85%RH Max;
 - 8.Storage Temperature:−40°C~+85°C 85%RH Max.
 - 9.Wave Solder 260°C,3~5 Seconds
IR Reflow, Peak Temp 230~260°C,60~90SEC;
 - 10.Sign"▲"is importance dimension.

NO.	CODE	MATERIAL	REMARK
2	L1	PA9T UL94V-0	RoHS2&H-F(IR Reflow)
1	L0	PA9T UL94V-0	RoHS2(IR Reflow)

TABLE A : Plastical Material



P/N: UB1195W-XXXX-XXXXXXX

Model P/N
Plastical Material (Choose From Table A)
Housing Color
□80:Yellow(1070C)

Typ
30:usb3.0-A;

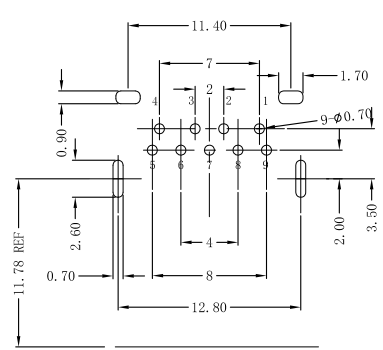
Product salt mist
□A:Normal(8 Hours);
□B:24Hours;

Packing
□B:Tray; □R:Tape reel;

Remark
0:Normal;
1:With CAP

Shell Material
□S:SUS

Plating Code
□A:CONTACT AREA:GOLD FALSH,SOLDER AREA:MATTE TIN80U"
□B:CONTACT AREA:3U"GOLD,SOLDER AREA:MATTE TIN80U"
□C:CONTACT AREA:5U"GOLD,SOLDER AREA:MATTE TIN80U"
□E:CONTACT AREA:15U"GOLD,SOLDER AREA:MATTE TIN80U"
□G:CONTACT AREA:30U"GOLD,SOLDER AREA:MATTE TIN80U"



TOLERANCE: ±0.05, THICKNESS: 1.6mm
RECOMMENDED PCB LAYOUT
(TOP VIEW)

NO.	DESCRIPTION	QTY	PARTS MATERIAL	PLATING OR COLOR	REMARK
4	SHIELD	1	SUS201	50u"MIN.NICEL ALL OVER	X
3	TERMINAL	5	Copper Alloy	50u" MIN NICKEL ALL OVER 80u"MIN Tin ON SOLDER AREA	X
2	TERMINAL	4	Copper Alloy		X
1	HOUSING	1	Choose from P/N	Choose from P/N item color	X

Tolerance X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 Angle ±3.0°	MODEL NAME:USB3.1 單層90度DIP MODEL No: UB1195W-XXXX-XXXXXXX	DRAWING: Peter Wang CHECKED: David Zhou APPROVED:Jacky Lee DATE: 2018.08.31
UNIT:mm	SCALE:1:1 REVISION A0 SHEET 1/1	FILE: CD/LINGYANG DWG NO.UB1195W-A001

